

## Dual P-Channel Power MOSFET

-20V, -3.7A, 140mΩ

### FEATURES

- 1.8V drive
- Pb-free plating
- RoHS compliant
- Halogen-free

### APPLICATIONS

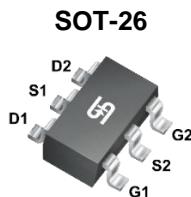
- Power management
- Load switch

PRODUCT SUMMARY		
PARAMETER	VALUE	UNIT
$V_{DS}$	-20	V
$R_{DS(on)}$ (max)	$V_{GS} = -4.5V$	140
	$V_{GS} = -2.5V$	200
	$V_{GS} = -1.8V$	300
$Q_g$	$V_{GS} = -4.5V$	7 nC

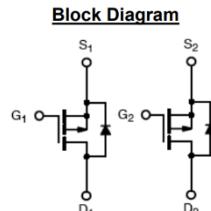


ROHS  
COMPLIANT

HALOGEN  
FREE



Block Diagram



Dual P-Channel MOSFET

Note: MSL 3 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Continuous Drain Current	$I_D$	-3.7	A
Pulsed Drain Current (Note 1)	$I_{DM}$	-14.8	A
Total Power Dissipation	$T_C = 25^\circ C$	2.7	W
		1.7	
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	°C

THERMAL RESISTANCE			
PARAMETER	SYMBOL	MAXIMUM	UNIT
Thermal Resistance – Junction to Case	$R_{eJC}$	45	°C/W
Thermal Resistance – Junction to Ambient (Note 2)	$R_{eJA}$	128	°C/W

**Note:**

1. Pulsed width limited by maximum junction temperature pulse Width  $\leq 100\mu s$ .
2. Device on a PCB FR4 with 1 in<sup>2</sup> (single layer, 2 oz thick) copper area for drain connection.

<b>ELECTRICAL CHARACTERISTICS</b> ( $T_A = 25^\circ\text{C}$ unless otherwise noted)						
<b>PARAMETER</b>	<b>CONDITIONS</b>	<b>SYMBOL</b>	<b>MIN</b>	<b>TYP</b>	<b>MAX</b>	<b>UNIT</b>
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu\text{A}$	$BV_{DSS}$	-20	--	--	V
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250\mu\text{A}$	$V_{GS(\text{TH})}$	-0.45	-0.7	-0.95	V
Gate-Source Leakage Current	$V_{GS} = \pm 8V, V_{DS} = 0V$	$I_{GSS}$	--	--	$\pm 100$	nA
Drain-Source Leakage Current	$V_{GS} = 0V, V_{DS} = -16V$	$I_{DSS}$	--	--	-1	$\mu\text{A}$
Drain-Source On-State Resistance <small>(Note 3)</small>	$V_{GS} = -4.5V, I_D = -2.2\text{A}$	$R_{DS(\text{on})}$	--	63	140	$\text{m}\Omega$
	$V_{GS} = -2.5V, I_D = -1.8\text{A}$		--	79	200	
	$V_{GS} = -1.8V, I_D = -1\text{A}$		--	103	300	
Forward Transconductance	$V_{DS} = -5V, I_D = -2.2\text{A}$	$g_{fs}$	--	11	--	S
<b>Dynamic</b>						
Total Gate Charge	$V_{GS} = -4.5V, V_{DS} = -6V, I_D = -2.2\text{A}$	$Q_g$	--	7	--	nC
Gate-Source Charge		$Q_{gs}$	--	0.8	--	
Gate-Drain Charge		$Q_{gd}$	--	1.6	--	
Input Capacitance	$V_{GS} = 0V, V_{DS} = -6V, f = 1.0\text{MHz}$	$C_{iss}$	--	596	--	pF
Output Capacitance		$C_{oss}$	--	71	--	
Reverse Transfer Capacitance		$C_{rss}$	--	66	--	
<b>Switching</b> <small>(Note 4)</small>						
Turn-On Delay Time	$V_{GS} = -4.5V, V_{DD} = -6V, I_D = -2.2\text{A}, R_G = 3.3\Omega$	$t_{d(on)}$	--	7.8	--	ns
Rise Time		$t_r$	--	36	--	
Turn-Off Delay Time		$t_{d(off)}$	--	84	--	
Fall Time		$t_f$	--	48	--	
<b>Source-Drain Diode</b>						
Diode Forward Voltage <small>(Note 3)</small>	$V_{GS} = 0V, I_S = -1.05\text{A}$	$V_{SD}$	--	-0.8	-1.2	V

**Notes:**

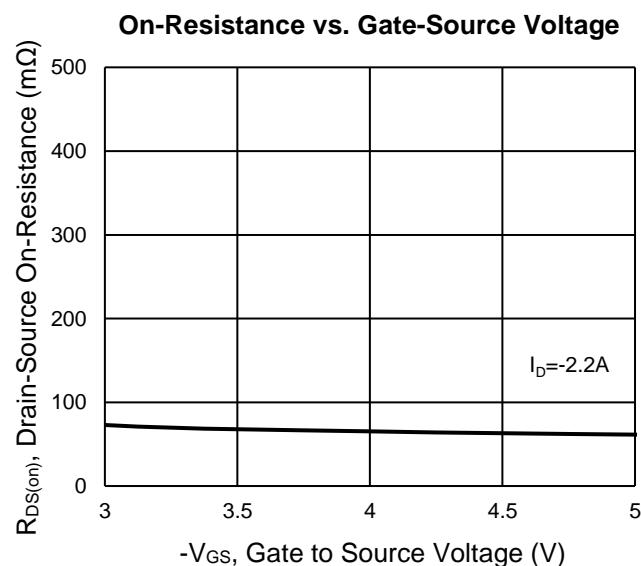
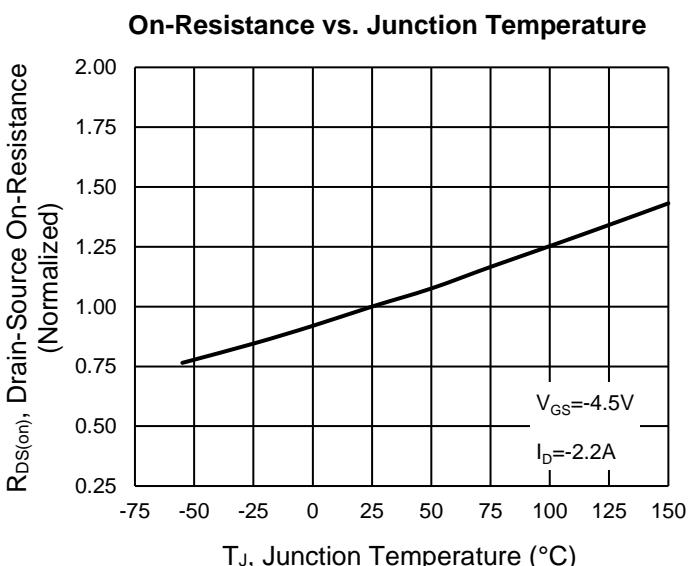
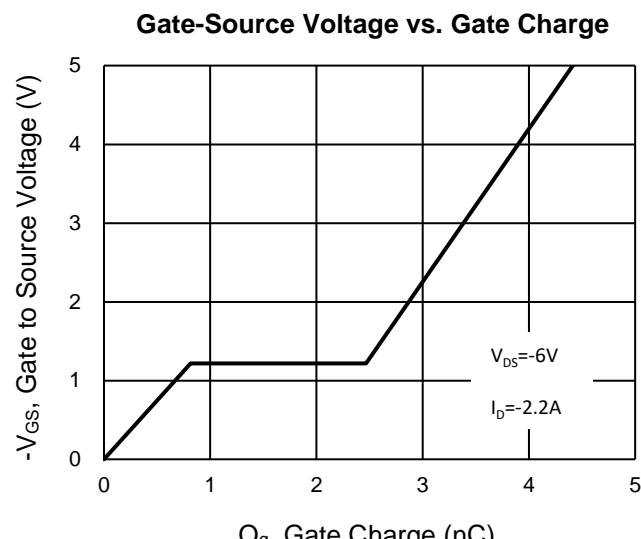
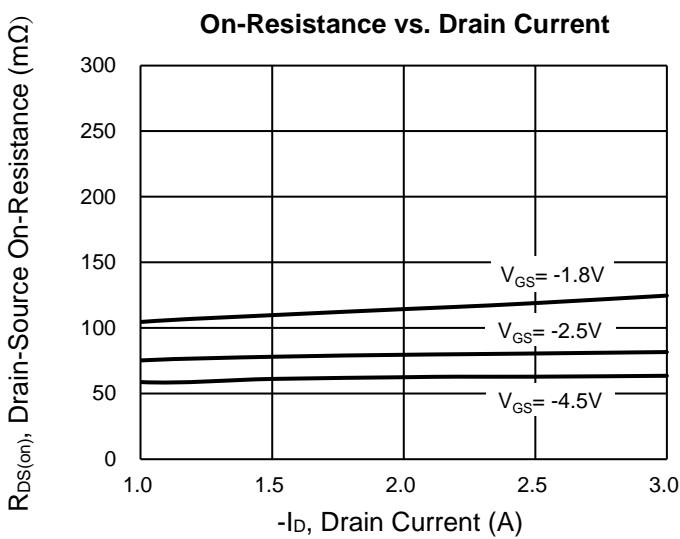
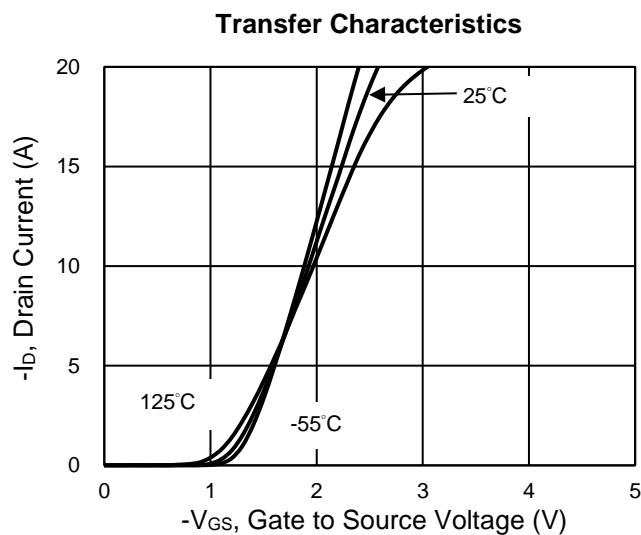
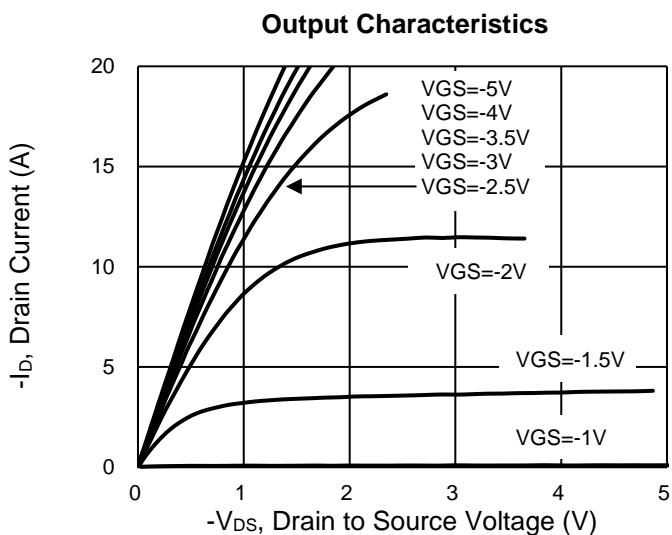
3. Pulse test: Pulse Width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
4. Switching time is essentially independent of operating temperature.

**ORDERING INFORMATION**

<b>ORDERING CODE</b>	<b>PACKAGE</b>	<b>PACKING</b>
TSM3911DCX6 RFG	SOT-26	3kpcs / 7" Reel

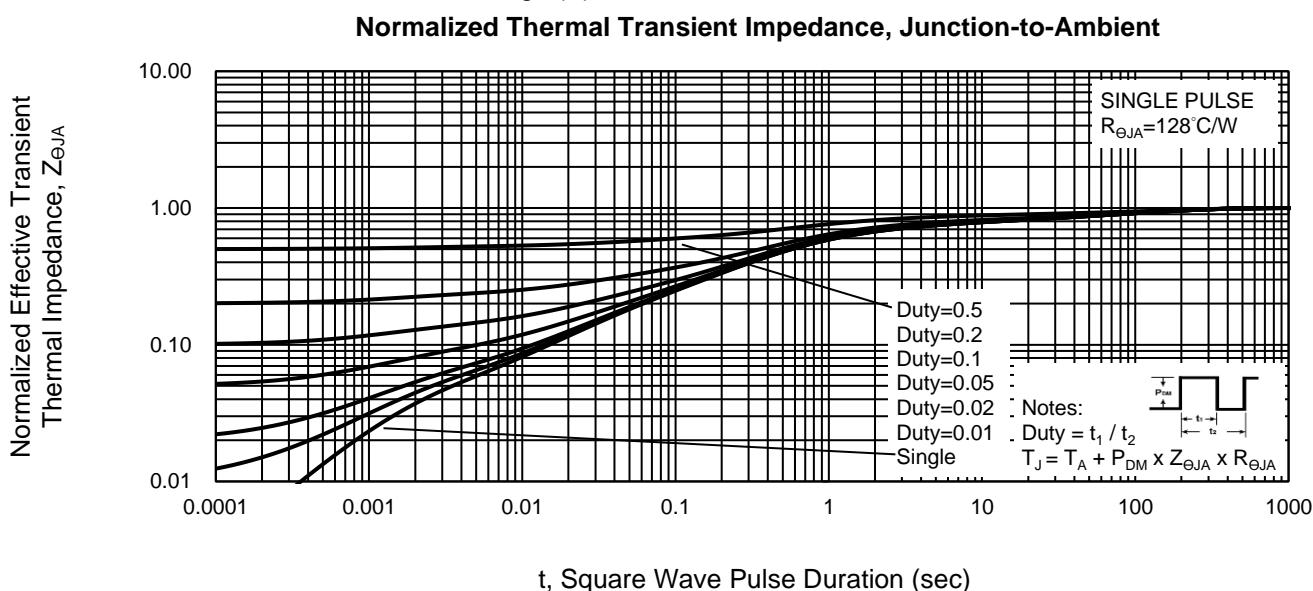
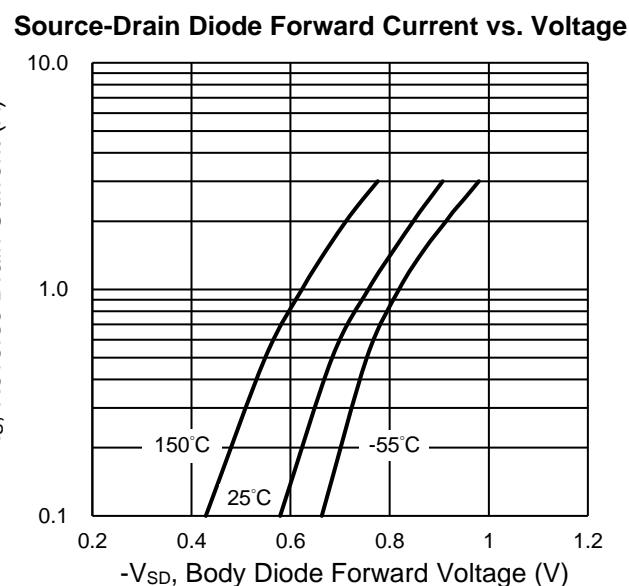
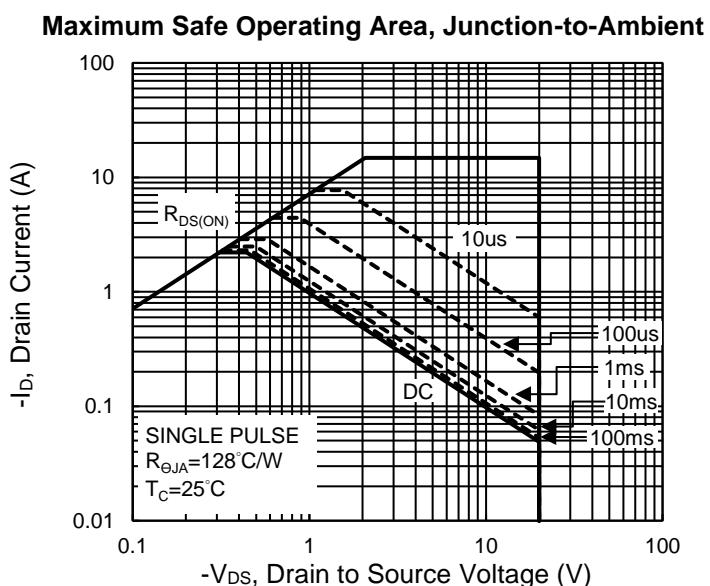
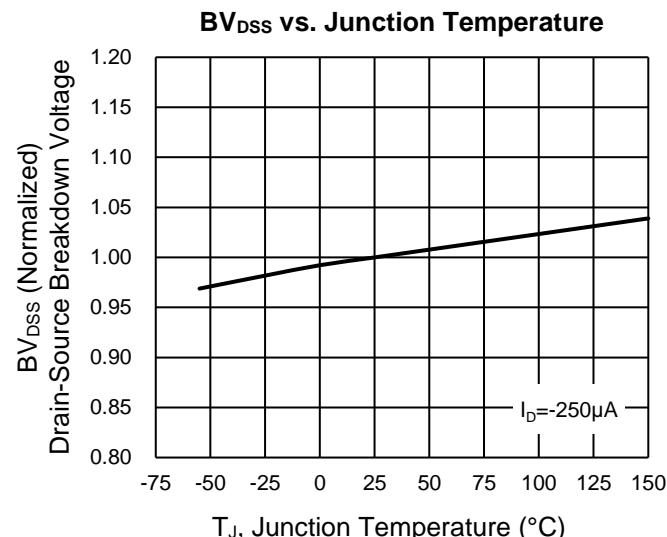
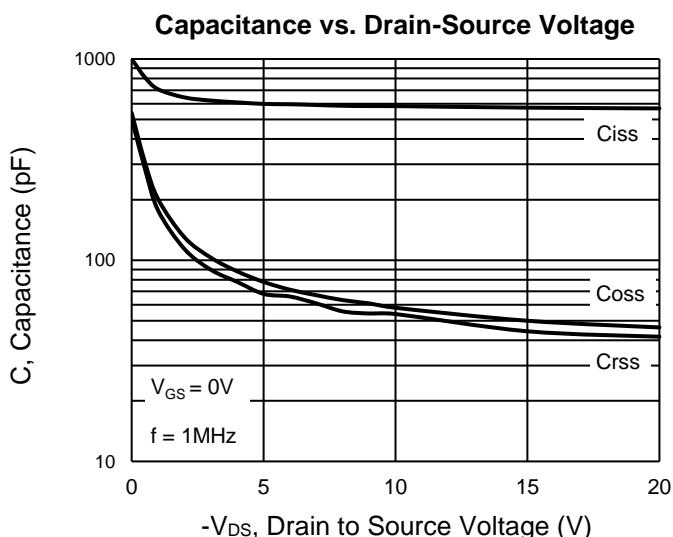
## CHARACTERISTICS CURVES

( $T_A = 25^\circ\text{C}$  unless otherwise noted)



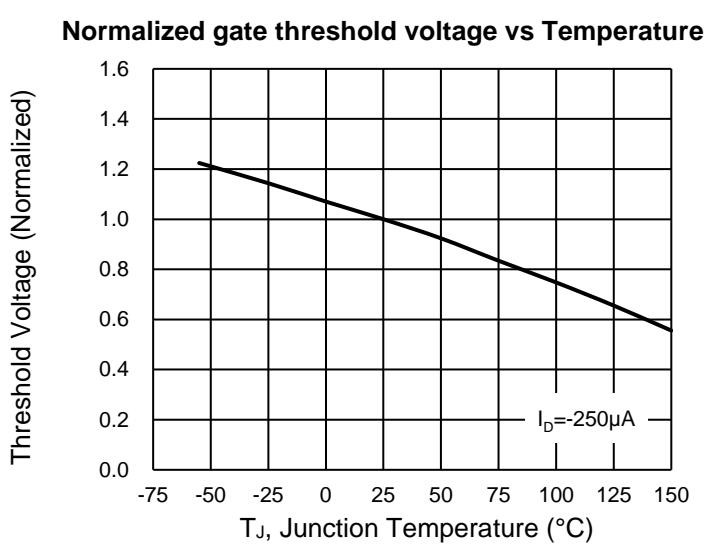
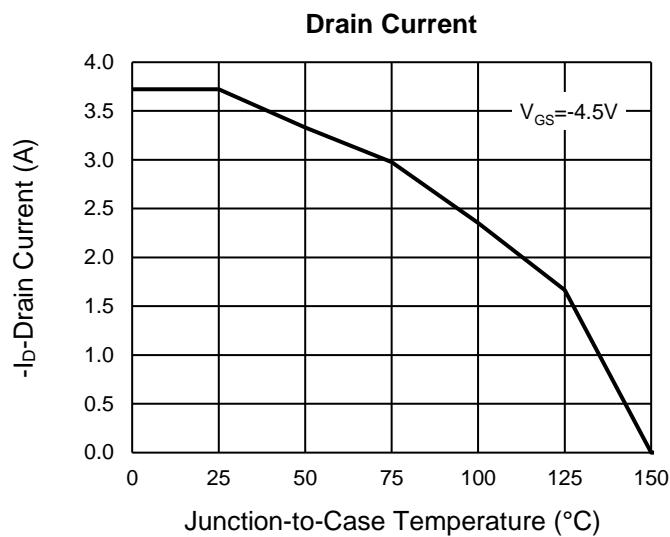
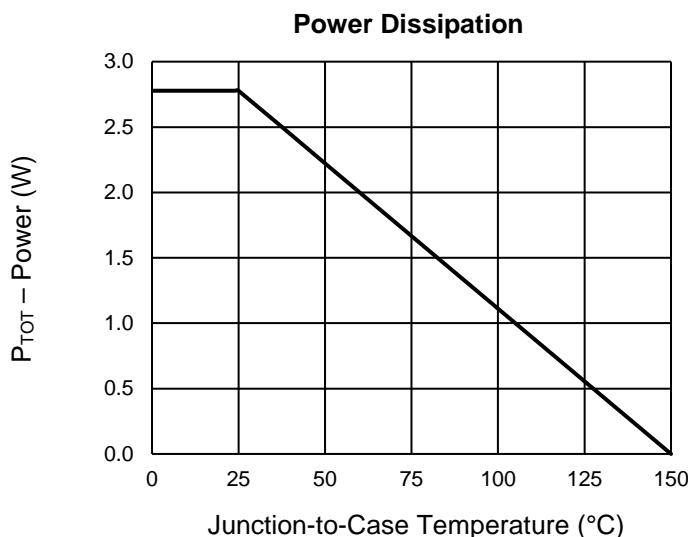
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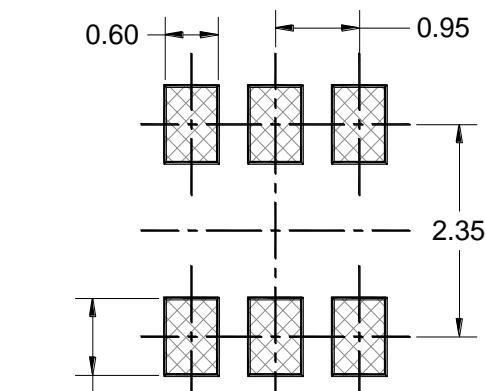
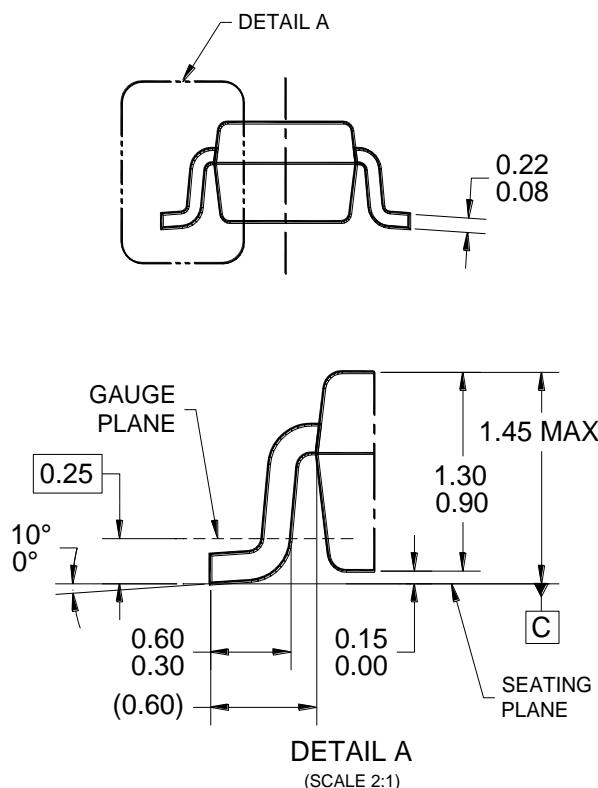
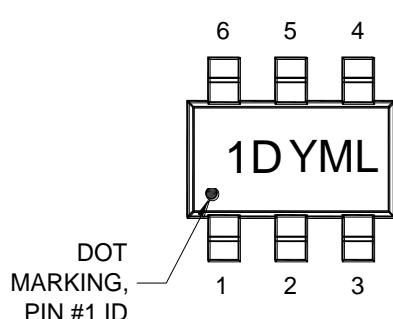
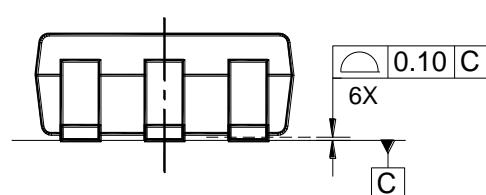
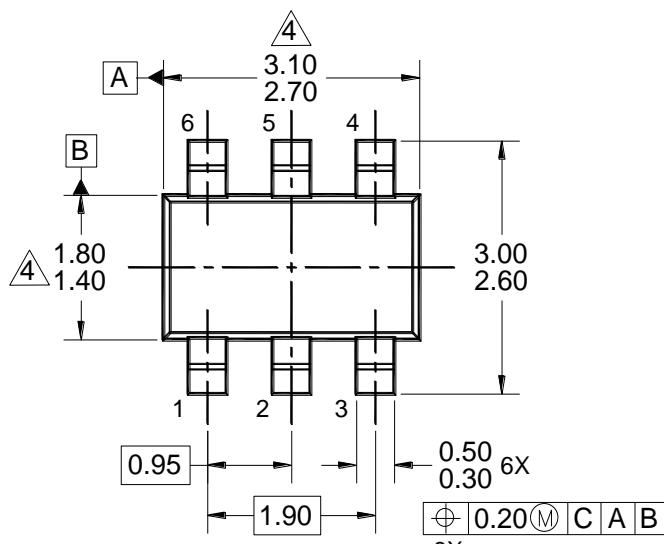


## CHARACTERISTICS CURVES

( $T_A = 25^\circ\text{C}$  unless otherwise noted)



**PACKAGE OUTLINE DIMENSIONS** (Unit: Millimeters)

**SOT-26**

**SUGGESTED PAD LAYOUT**

NOTES: UNLESS OTHERWISE SPECIFIED

- Y** = YEAR CODE  
**M** = MONTH CODE FOR HALOGEN FREE PRODUCT  
 O = JAN P = FEB Q = MAR R = APR  
 S = MAY T = JUN U = JUL V = AUG  
 W = SEP X = OCT Y = NOV Z = DEC  
**L** = LOT CODE

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PACKAGE OUTLINE REFERENCE: JEDEC MO-178, VARIATION AB.
- △** MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DWG NO. REF: HQ2SD07-SOT26-027 REV A.

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